



60V N-CHANNEL ENHANCEMENT MODE MOSFET POWERDI

Product Summary

V _{(BR)DSS}	R _{DS(ON)} Max	I _D Max T _A = +25°C
60V	13mΩ @ V _{GS} = 10V	10.3A
	18mO @ Vcs = 4.5V	8.8A

Features and Benefits

- Low R_{DS(ON)}—Ensures On-state Losses are Minimized
- Small Form Factor Thermally Efficient Package Enables Higher Density End Products
- Occupies Just 33% of Board Area Occupied by SO-8 Enabling Smaller End Product
- Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

Description

This MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) yet maintain superior switching performance, which makes it ideal for high-efficiency power management applications.

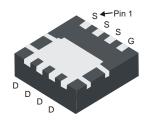
Applications

- Backlighting
- Power Management Functions
- DC-DC Converters

Mechanical Data

- Case: PowerDI[®]3333-8
- Case Material: Molded Plastic, "Green" Molding Compound UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminal Connections Indicator: See diagram
- Terminals: Finish—Matte Tin Annealed over Copper Leadframe Solderable per MIL-STD-202, Method 208 (3)
- Weight: 0.072 grams (Approximate)

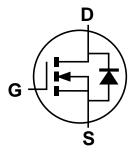
PowerDI3333-8



Bottom View



Top View



Equivalent Circuit

Ordering Information (Note 4)

Part Number	Case	Packaging
DMN6013LFG-7	PowerDI3333-8	2000/Tape & Reel
DMN6013LFG-13	PowerDI3333-8	3000/Tape & Reel

Notes:

- 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS), 2011/65/EU (RoHS 2) & 2015/863/EU (RoHS 3) compliant.
- 2. See https://www.diodes.com/quality/lead-free/ for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
- 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
- 4. For packaging details, go to our website at http"//www.diodes.com/products/packages.html.

Marking Information



N63= Product Type Marking Code YYWW = Date Code Marking YY = Last digit of year (ex: 18 = 2018) WW = Week code (01 ~ 53)



Maximum Ratings (@ $T_A = +25$ °C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Drain-Source Voltage	V_{DSS}	60	V	
Gate-Source Voltage	V_{GSS}	±20	V	
Continuous Drain Current (Note 6) $V_{GS} = 10V$ $T_A = +25^{\circ}$ $T_C = +25^{\circ}$ $T_C = +100^{\circ}$		l _D	10.3 8.3	А
		I _D	45 28	А
Pulsed Drain Current (10µs Pulse, Duty Cycle = 1%)	I _{DM}	58.3	Α	
Maximum Continuous Body Diode Forward Current (Note 6)	Is	3	Α	
Avalanche Current, L = 0.1mH	I _{AS}	33.3	Α	
Avalanche Energy, L = 0.1mH	E _{AS}	56.8	mJ	

Thermal Characteristics (@T_A = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Units	
Total Power Dissipation (Note 5)		P_D	1	W
Thermal Resistance, Junction to Ambient (Note 5)	Steady state	D	123	°C/W
Thermal Resistance, Junction to Ambient (Note 5)	t < 10s	- R _{⊖JA}	69	
Total Power Dissipation (Note 6)		P_D	2.1	W
Thermal Resistance, Junction to Ambient (Note 6)	Steady state	Reja	60	°C/W
Thermal Nesistance, sunction to Ambient (Note 0)	t < 10s	КӨЈА	34	
Total Power Dissipation (Note 6)		P_D	40	W
Thermal Resistance, Junction to Case (Note 6)		Rejc	3.2	°C/W
Operating and Storage Temperature Range		T _{J,} T _{STG}	-55 to +150	°C

Electrical Characteristics (@T_A = +25°C, unless otherwise specified.)

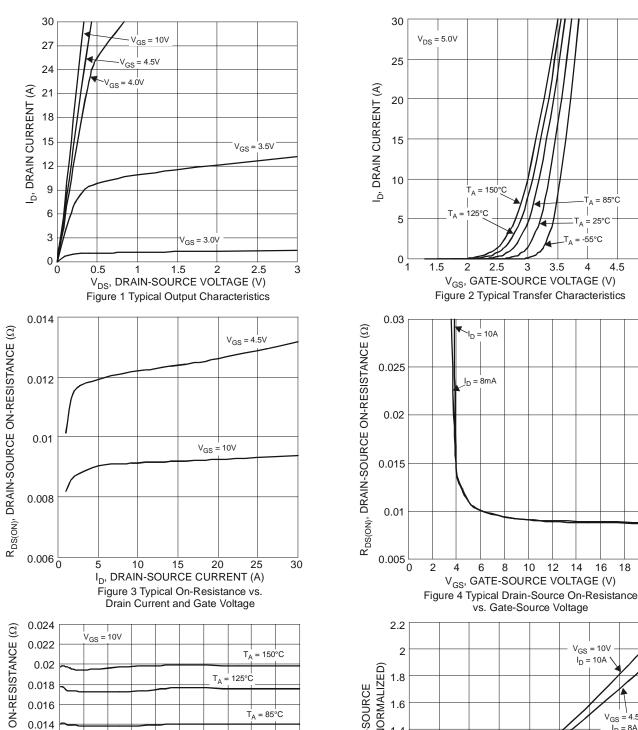
Characteristic		Min	Тур	Max	Unit	Test Condition	
OFF CHARACTERISTICS (Note 7)							
Drain-Source Breakdown Voltage		60	_	_	V	$V_{GS} = 0V, I_D = 250\mu A$	
Zero Gate Voltage Drain Current, T _J = +25°C	I _{DSS}	_	_	1	μA	$V_{DS} = 60V, V_{GS} = 0V$	
Gate-Source Leakage	I _{GSS}	_	_	±100	nA	$V_{GS} = \pm 20V, V_{DS} = 0V$	
ON CHARACTERISTICS (Note 7)							
Gate Threshold Voltage	V _{GS(th)}	1	1.8	3	V	$V_{DS} = V_{GS}$, $I_D = 250\mu A$	
Static Drain-Source On-Resistance	D	_	9.3	13	mΩ	$V_{GS} = 10V, I_D = 10A$	
Static Dialif-Source Off-Resistance	R _{DS(ON)}	_	12.3	18	mt2	$V_{GS} = 4.5V, I_D = 8A$	
Diode Forward Voltage	V_{SD}	_	0.7	1.2	V	$V_{GS} = 0V, I_{S} = 1.7A$	
DYNAMIC CHARACTERISTICS (Note 8)				•		•	
Input Capacitance	C _{iss}	_	2577	_	pF		
Output Capacitance	Coss	_	162	_	pF	$V_{DS} = 30V, V_{GS} = 0V,$ f = 1MHz	
Reverse Transfer Capacitance	Crss	_	132	_	pF	-1 = 11V1172	
Gate Resistance	Rg	_	0.9	_	Ω	$V_{DS} = 0V$, $V_{GS} = 0V$, $f = 1MHz$	
Total Gate Charge (V _{GS} = 4.5V)	Qg	_	26.6	_	nC		
Total Gate Charge (V _{GS} = 10V)	Qg	_	55.4	_	nC	201/ 1 404	
Gate-Source Charge	Q _{gs}	_	9.3	_	nC	$V_{DS} = 30V, I_{D} = 10A$	
Gate-Drain Charge	Q_{gd}	_	12.6	_	nC	1	
Turn-On Delay Time	t _{D(on)}	_	6.2	_	ns	$V_{GS} = 10V, V_{DS} = 30V,$ $R_G = 3\Omega, I_D = 10A$	
Turn-On Rise Time	t _r	_	9.9	_	ns		
Turn-Off Delay Time	t _{D(off)}	_	27.6	_	ns		
Turn-Off Fall Time	t _f	_	11.7	_	ns		
Body Diode Reverse Recovery Time	t _{rr}	_	9.4	_	nS	1. 404 11/14 4004/-	
Body Diode Reverse Recovery Charge	Q _{rr}	_	18.6	_	nC	I _F = 10A, di/dt = 100A/μs	

Notes:

- 5. Device mounted on FR-4 PCB, with minimum recommended pad layout, single sided.
- 6. Device mounted on FR-4 substrate PCB, 2oz copper, with thermal bias to bottom layer 1inch square copper plate 7. Short duration pulse test used to minimize self-heating effect.
- 8. Guaranteed by design. Not subject to product testing.

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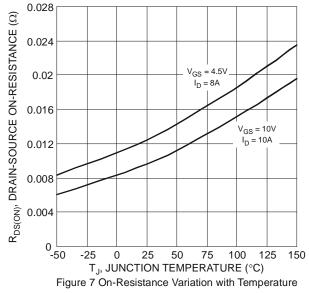


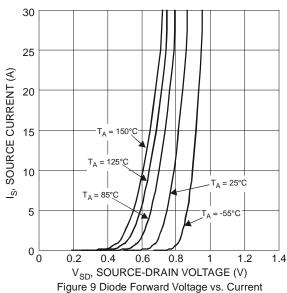


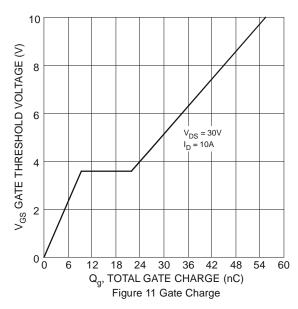
 $R_{DS(ON)}$, DRAIN-SOURCE ON-RESISTANCE (Ω) 0.014 0.012 T_A = 25°C 0.01 0.008 T_A = -55°C 0.006 0.004 0.002 0 _ 2 8 10 12 14 16 I_D, DRAIN CURRENT (A) Figure 5 Typical On-Resistance vs.

Drain Current and Temperature









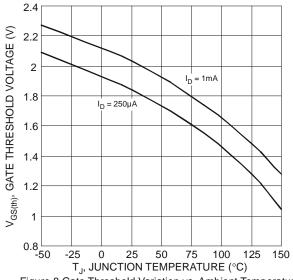
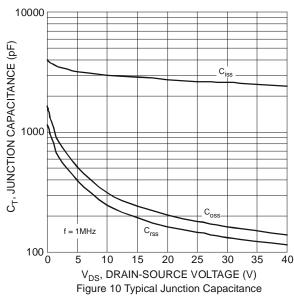
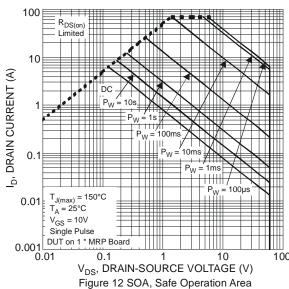
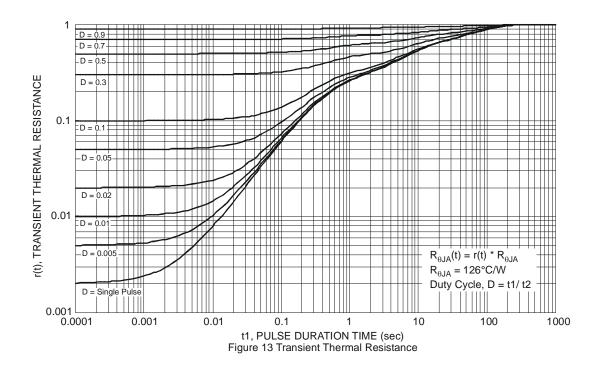


Figure 8 Gate Threshold Variation vs. Ambient Temperature







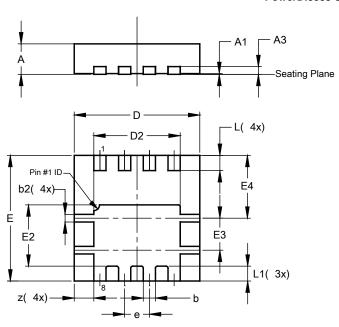




Package Outline Dimensions

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8

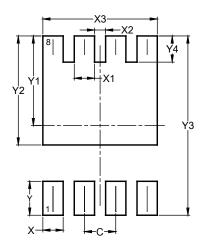


PowerDI3333-8					
Dim	Min	Max	Тур		
Α	0.75	0.85	0.80		
A1	0.00	0.05	0.02		
А3	_		0.203		
b	0.27	0.37	0.32		
b2	0.15	0.25	0.20		
D	3.25	3.35	3.30		
D2	2.22	2.32	2.27		
Е	3.25	3.35	3.30		
E2	1.56	1.66	1.61		
E3	0.79	0.89	0.84		
E4	1.60	1.70	1.65		
е	_		0.65		
L	0.35	0.45	0.40		
L1			0.39		
Z			0.515		
All Dimensions in mm					

Suggested Pad Layout

Please see http://www.diodes.com/package-outlines.html for the latest version.

PowerDI3333-8



Dimensions	Value (in mm)
С	0.650
X	0.420
X1	0.420
X2	0.230
Х3	2.370
Y	0.700
Y1	1.850
Y2	2.250
Y3	3.700
Y4	0.540

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